

*L' cond.* and

*M*  
a third chamber capable of taking said substrate out of said multi-chamber system after depositing said gate insulating film.

---

*L2* 86. (Amended) A multi-chamber system comprising:

a first chamber for irradiating a laser light to a semiconductor film formed over a substrate;

a means for introducing an oxidizing atmosphere into said first chamber;

a second chamber for depositing a gate insulating film on said semiconductor film;

a third chamber capable of taking said substrate out of said multi-chamber system after depositing said gate insulating film; and

a means for transporting said substrate among said first, second and third chambers.

---

*L3* 92. (Amended) A multi-chamber system comprising:

a first chamber for irradiating a laser light to a semiconductor film formed over a substrate;

a means for introducing an oxidizing atmosphere into said first chamber;

a second chamber for depositing a gate insulating film; and

a third chamber for putting said substrate in said multi-chamber system and for taking said substrate out of said multi-chamber system,

wherein said multi-chamber system is capable of depositing said gate insulating film on said semiconductor film irradiated with said laser light.

---

*L4* 98. (Amended) A multi-chamber system comprising:

*M*  
a first chamber for irradiating a laser light to a semiconductor film formed over a

substrate;

a means for introducing an oxidizing atmosphere into said first chamber;

a second chamber for depositing a gate insulating film;

*l4*  
*crnd.*  
a third chamber for putting said substrate in said multi-chamber system and for taking said substrate out of said multi-chamber system; and

a means for transporting said substrate among said first, second and third chambers,

wherein said multi-chamber system is capable of depositing said gate insulating film on said semiconductor film irradiated with said laser light.

---

Please add new claims 136-153 as follows:

---

--136. (New) A multi-chamber system according to claim 80 wherein said means for introducing said oxidizing gas is a gas intake valve.

*l5*  
137. (New) A multi-chamber system according to claim 86 wherein said means for introducing said oxidizing gas is a gas intake valve.

138. (New) A multi-chamber system according to claim 92 wherein said means for introducing said oxidizing gas is a gas intake valve.

139. (New) A multi-chamber system according to claim 98 wherein said means for introducing said oxidizing gas is a gas intake valve.

140. (New) A multi-chamber system comprising:

a first chamber for irradiating a laser light to a semiconductor film formed over a

substrate;

a means for introducing an oxidizing atmosphere into said first chamber;

a second chamber for depositing an insulating film on said semiconductor film; and

a third chamber capable of taking said substrate out of said multi-chamber system.

141. (New) A multi-chamber system according to claim 140 wherein said second chamber is selected from the group consisting of a plasma CVD apparatus, a low pressure CVD apparatus, an atmospheric pressure CVD apparatus and a sputtering film formation apparatus.

142. (New) A multi-chamber system according to claim 141 wherein a silicon oxide film is formed by one of said apparatus.

143. (New) A multi-chamber system according to claim 140 wherein said laser comprises an excimer laser or a YAG laser.

144. (New) A multi-chamber system according to claim 140 wherein said laser light has a rectangular shape on an irradiating surface.

145. (New) A multi-chamber system according to claim 140 wherein said oxidizing atmosphere comprises oxygen.

146. (New) A multi-chamber system according to claim 140 wherein said means for introducing said oxidizing gas is a gas intake valve.

147. (New) A multi-chamber system comprising:  
a first chamber for irradiating a laser light to a semiconductor film formed over a substrate;  
a means for introducing an oxidizing atmosphere into said first chamber;  
a second chamber for depositing an insulating film on said semiconductor film; and  
a third chamber for putting said substrate in said multi-chamber system and for taking said substrate out of said multi-chamber system.

*L5 Cont.*  
148. (New) A multi-chamber system according to claim 147 wherein said second chamber is selected from the group consisting of a plasma CVD apparatus, a low pressure CVD apparatus, an atmospheric pressure CVD apparatus and a sputtering film formation apparatus.

149. (New) A multi-chamber system according to claim 148 wherein a silicon oxide film is formed by one of said apparatus.

150. (New) A multi-chamber system according to claim 147 wherein said laser comprises an excimer laser or a YAG laser.

151. (New) A multi-chamber system according to claim 147 wherein said laser light has a rectangular shape on an irradiating surface.

152. (New) A multi-chamber system according to claim 147 wherein said oxidizing atmosphere comprises oxygen.